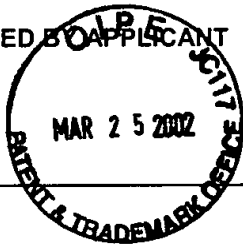


LIST OF REFERENCES CITED BY APPLICANT (Use several sheets if necessary)	ATTY. DOCKET NO. 100665.0044US1	SERIAL NO. 10/026,338
	APPLICANT Jesse Pedigo	
	FILING DATE 12/20/01	GROUP 1725
	RECEIVED MAR 28 2002 TC 1700	



U.S. PATENT DOCUMENTS

EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
KS	3,601,523	08/24/71	Through Hole Connectors	174	68.5	06/19/70
	4,106,187	08/15/78	Curved Rigid Printed Circuit Boards	29	625	01/16/76
	4,283,243	08/11/81	Use of Photosensitive Stratum to Create Through-Hole Connections in Circuit Boards	156	237	03/20/80
	4,360,570	11/23/82	Use of Photosensitive Stratum to Create Through-Hole Connections in Circuit Boards	428	596	06/15/81
	4,622,239	11/11/86	Method and Apparatus for Dispensing Viscous Materials	427	96	02/18/86
	4,700,474	10/20/87	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards	29	846	11/26/86
	4,777,721	10/18/88	Apparatus and Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87
	4,783,247	11/8/88	Method and Manufacture for Electrically Insulating Base Material Used in Plated-Through Printed Circuit Panels	204	181.1	05/15/86
	4,884,337	12/05/89	Method for Temporarily Sealing Holes in Printed Circuit Boards Utilizing a Thermodeformable Material	29	846	10/15/87
	4,964,948	10/23/90	Printed Circuit Board Through Hole Technique	156	659	11/13/89
	4,995,941	02/26/91	Method of Manufacture Interconnect Device	156	630	05/15/89
	5,053,921	10/01/91	Multilayer Interconnect Device and Method of Manufacture Thereof	361	386	10/23/90
	5,058,265	10/22/91	Method for Packaging a Board of Electronic Components	29	852	09/10/90
	5,145,691	09/08/92	Apparatus for Packing Filler into Through-Holes or the Like in a Printed Circuit Board	425	110	03/22/91
	5,220,723	06/22/93	Process for Preparing Multi-Layer Printed Wiring Board	29	830	11/04/91
	5,274,916	01/04/94	Method of Manufacturing Ceramic Multilayer Electronic Component	29	848	12/17/92
	5,451,721	09/19/95	Multilayer Printed Circuit Board and Method for Fabricating Same	174	261	09/24/91
KS	5,456,004	10/10/95	Anisotropic Interconnect Methodology for Cost Effective Manufacture of High Density Printed Circuit Boards	29	852	01/04/94

Wiley 7-8-03

KS	5,471,091	01/28/95	Techniques for Via Formation and Filling	257	752	08/26/91
	5,532,326	07/02/96	Techniques for Via Formation and Filling	257	752	03/28/95
	5,540,775	07/30/96	Apparatus for Manufacture of Multi-Layer Ceramic Interconnect Structures	118	692	03/01/95
	5,578,151	11/26/96	Manufacture of A Multi-Layer Interconnect Structure	156	64	03/01/95
	5,591,353	01/07/97	Reduction of Surface Copper Thickness on Surface Mount Printed Wire Boards with Copper Plated Through Holes by the Chemical Planarization Method	216	18	08/18/94
	5,610,103	03/11/97	Ultrasonic Wave Assisted Contact Hole Filling	437	225	12/12/95
	5,637,834	06/10/97	Multilayer Circuit Substrate and Method for Forming Same	174	264	02/03/95
	5,662,987	09/02/97	Multilayer Printed Wiring Board and Method of Making Same	428	209	02/01/96
	5,699,613	12/23/97	Fine Dimension Stacked Vias for a Multiple Layer Circuit Board Structure	29	852	09/25/95
	5,744,285	04/28/98	Composition and Process for Filling Vias	430	318	07/18/96
	5,753,976	05/19/98	Multi-Layer Circuit Having a Via Matrix Interlayer Connection	257	774	06/14/96
	5,761,803	06/09/98	Method of Forming Plugs in Vias of A Circuit Board by Utilizing a Porous Membrane	29	852	06/26/96
	5,766,670,	06/16/98	Via Fill Compositions for Direct Attach of Devices and Methods for Applying Same	427	8	11/17/93
	5,822,856	10/20/98	Manufacturing Circuit Boards Assemblies Having Filled Vias	29	832	06/28/96
KS	5,824,155	10/20/98	Method and Apparatus for Dispensing Viscous Material	118	410	11/08/95

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

EXAMINER <i>Kley</i>	DATE CONSIDERED 7-8-03
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ATTY. Docket NO.
100970.665044US2

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10/026338

APPLICANT
Pedigo, Jesse et al

FILING DATE
20 December 2001

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U.S. PATENT DOCUMENTS

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
KS	AA	6,193,144	02/27/01	Paste Providing Method, Soldering Method and Apparatus and System Therefor	228	248	06/22/98
KS	BB	6,491,204	12/10/02	Stencil Wiping Device	228	22	11/22/00
	CC						
	DD						
	EE						
	FF						
	GG						
	HH						
	II						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
	JJ						YES	NO
	KK							
	LL							
	MM							
	NN							

OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, Etc.)

KS	OO	Shoji Oikawa et al., Solder Coating Device, May 27, 1987, pages unknown
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EXAMINER <i>Ally H...</i>	DATE CONSIDERED 7-8-03
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